IN THE CLAIMS

Please amend the claims as follows:

1-21. (Canceled)

22. (New) A substrate comprising:

a first conductive layer between a first dielectric layer and a second dielectric layer, the first conductive layer including a first skip via extending through the first dielectric layer and a third dielectric layer; and

a second conductive layer on the second dielectric layer, the second conductive layer including a second via extending through the second dielectric layer, the second via and the first skip via being stacked on top of one another.

23. (New) The substrate of claim 22 wherein the first skip via includes a longitudinal axis and the second via includes a longitudinal axis, the longitudinal axis of the first skip via being substantially aligned with the longitudinal axis of the second via.

24. (New) The substrate of claim 22 wherein first, second and third dielectric layers are formed on a core and the first and second conductive layers are formed on the core.

25. (New) The substrate of claim 22 wherein the second conductive layer is between the second dielectric layer and a fourth dielectric layer.

26. (New) The substrate of claim 25 further comprising a third conductive layer on the fourth dielectric layer, the third conductive layer including a third via extending through the fourth dielectric layer, the third via being stacked onto the first skip via and the second via.

27. (New) The substrate of claim 26 wherein the first skip via includes a longitudinal axis and the second and third vias each include a longitudinal axis, the longitudinal axis of the first skip via being substantially aligned with the longitudinal axis of the second via and the longitudinal axis of the third via.

28. (New) The substrate of claim 22 wherein the first conductive layer is a patterned conductive layer and the second conductive layer is a patterned conductive layer.

29. (New) The substrate of claim 22 wherein the first skip via is cylindrical with a diameter between 49um and 85um and the second via is cylindrical with a diameter between 49um and 85um.

30. (New) The substrate of claim 22 wherein the first skip via has a length between 58um and 92um and the second via has a length between 24um and 36um.

31. (New) A substrate comprising:

a first conductive layer between a first dielectric layer and a second dielectric layer, the first conductive layer including a first skip via extending through the first dielectric layer and a third dielectric layer; and

a second conductive layer on a fourth dielectric layer, the second conductive layer including a second skip via extending through the second dielectric layer and the fourth dielectric layer, the first skip via and the second skip via being stacked on top of one another.

32. (New) The substrate of claim 31 wherein the first skip via includes a longitudinal axis and the second skip via includes a longitudinal axis, the longitudinal axis of the first skip via being substantially aligned with the longitudinal axis of the second skip via.

33. (New) The substrate of claim 31 wherein first, second, third and fourth dielectric layers are formed on a core and the first and second conductive layers are formed on the core.

34. (New) The substrate of claim 31 wherein the second conductive layer is between the fourth dielectric layer and a fifth dielectric layer.

35. (New) The substrate of claim 34 further comprising a third conductive layer on the fifth dielectric layer, the third conductive layer including a third via extending through the fifth dielectric layer, the third via being stacked onto the first skip via and the second skip via.

36. (New) The substrate of claim 35 wherein the first and second skip vias each include a longitudinal axis and the third via includes a longitudinal axis, the longitudinal axis of the first skip via being substantially aligned with the longitudinal axis of the second skip via and the longitudinal axis of the third via.

37. (New) The substrate of claim 31 wherein the first conductive layer is a patterned conductive layer and the second conductive layer is a patterned conductive layer.

38. (New) The substrate of claim 31 wherein the first skip via is cylindrical with a diameter between 49um and 85um and the second skip via is cylindrical with a diameter between 49um and 85um.

39. (New) The substrate of claim 31 wherein the first skip via has a length between 58um and 92um and the second skip via has a length between 58um and 92um.